

# High Efficiency Thyristor

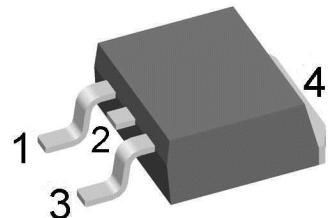
$V_{RRM}$  = 1200 V  
 $I_{TAV}$  = 20 A  
 $V_T$  = 1.54 V

## SemiFast Single Thyristor

### Part number

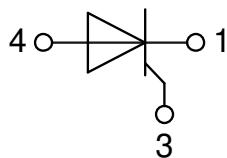
**CLE20E1200PC**

Marking on Product: *CLE20E1200PC*



Backside: anode

ESD Level: H3B



### Features / Advantages:

- Thyristor for line and moderate frequencies
- Short turn-off time
- Planar passivated chip
- Long-term stability

### Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

### Package: TO-263 (D2Pak)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

### Disclaimer Notice

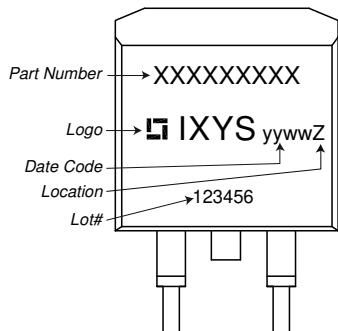
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**Thyristor**

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1300	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1200	V
$I_{R/D}$	reverse current, drain current	$V_{R/D} = 1200 V$ $V_{R/D} = 1200 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		100 2	$\mu A$ mA
$V_T$	forward voltage drop	$I_T = 20 A$	$T_{VJ} = 25^\circ C$		1.54	V
		$I_T = 40 A$			2.03	V
		$I_T = 20 A$	$T_{VJ} = 125^\circ C$		1.54	V
		$I_T = 40 A$			2.17	V
$I_{TAV}$	average forward current	$T_C = 95^\circ C$ 180° sine	$T_{VJ} = 150^\circ C$		20	A
$V_{T0}$	threshold voltage	$r_T$ slope resistance } for power loss calculation only	$T_{VJ} = 150^\circ C$		0.87	V
	slope resistance				34	$m\Omega$
$R_{thJC}$	thermal resistance junction to case				1	K/W
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W
$P_{tot}$	total power dissipation		$T_C = 25^\circ C$		125	W
$I_{TSM}$	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		160	A
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		175	A
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 150^\circ C$		135	A
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		145	A
$I^2t$	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		130	$A^2s$
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		125	$A^2s$
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 150^\circ C$		91	$A^2s$
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		87	$A^2s$
$C_J$	junction capacitance	$V_R = 400 V$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	7		pF
$P_{GM}$	max. gate power dissipation	$t_p = 30 \mu s$	$T_C = 150^\circ C$		5	W
		$t_p = 300 \mu s$			2.5	W
					0.5	W
$P_{GAV}$	average gate power dissipation					
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 125^\circ C; f = 50 \text{ Hz}$ repetitive, $I_T = 60 A$			100	$A/\mu s$
		$t_p = 200 \mu s; di_G/dt = 0.15 A/\mu s;$				
		$I_G = 0.15 A; V = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 20 A$			500	$A/\mu s$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^\circ C$		500	$V/\mu s$
		$R_{GK} = \infty$ ; method 1 (linear voltage rise)				
$V_{GT}$	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		1.5	V
			$T_{VJ} = -40^\circ C$		2.5	V
$I_{GT}$	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		40	$mA$
			$T_{VJ} = -40^\circ C$		70	$mA$
$V_{GD}$	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^\circ C$		0.2	V
$I_{GD}$	gate non-trigger current				3	$mA$
$I_L$	latching current	$t_p = 10 \mu s$ $I_G = 0.1 A; di_G/dt = 0.1 A/\mu s$	$T_{VJ} = 25^\circ C$		60	$mA$
$I_H$	holding current	$V_D = 6 V$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ C$		50	$mA$
$t_{gd}$	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^\circ C$		2	$\mu s$
		$I_G = 0.1 A; di_G/dt = 0.1 A/\mu s$				
$t_q$	turn-off time	$V_R = 20 V; I_T = 20 A; V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ C$ $di/dt = 10 A/\mu s$ $dv/dt = 1000 V/\mu s$ $t_p = 200 \mu s$		100		$\mu s$

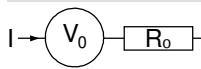
**Package TO-263 (D2Pak)**

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$I_{RMS}$	$RMS$ current	per terminal			35	A
$T_{VJ}$	virtual junction temperature		-40		150	°C
$T_{op}$	operation temperature		-40		125	°C
$T_{stg}$	storage temperature		-40		150	°C
<b>Weight</b>				1.5		g
$F_c$	mounting force with clip		20		60	N

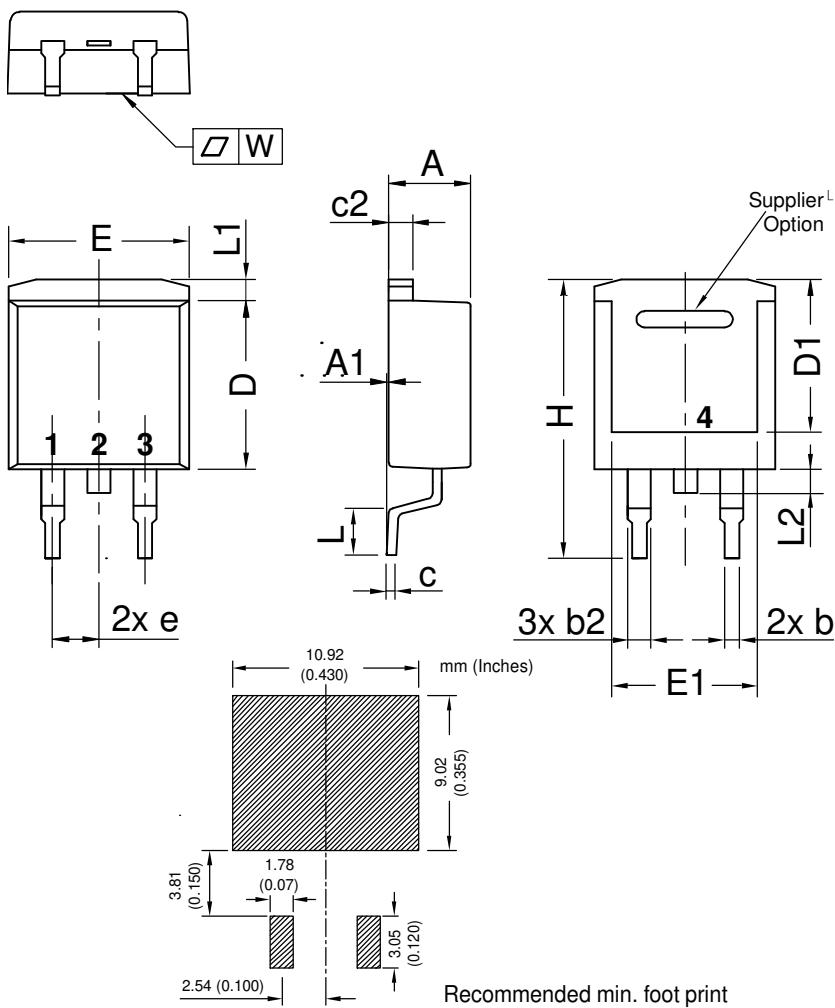
**Product Marking**

**Part description**

C = Thyristor (SCR)  
 L = High Efficiency Thyristor  
 E = Semifast (up to 1200V)  
 20 = Current Rating [A]  
 E = Single Thyristor  
 1200 = Reverse Voltage [V]  
 PC = TO-263AB (D2Pak) (2)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CLE20E1200PC-TRL	CLE20E1200PC	Tape & Reel	800	512774
Alternative	CLE20E1200PC-TUB	CLE20E1200PC	Tube	50	523602

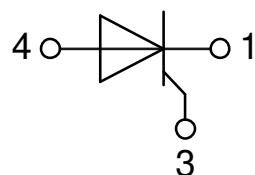
**Equivalent Circuits for Simulation**
*\* on die level*
 $T_{VJ} = 150^\circ\text{C}$ 

**Thyristor**

$V_{0\max}$  threshold voltage 0.87 V  
 $R_{0\max}$  slope resistance \* 36 mΩ

**Outlines TO-263 (D2Pak)**


Dim.	Millimeter		Inches	
	min	max	min	max
A	4.06	4.83	0.160	0.190
A1	typ. 0.10		typ. 0.004	
A2	2.41		0.095	
b	0.51	0.99	0.020	0.039
b2	1.14	1.40	0.045	0.055
c	0.40	0.74	0.016	0.029
c2	1.14	1.40	0.045	0.055
D	8.38	9.40	0.330	0.370
D1	8.00	8.89	0.315	0.350
D2	2.5		0.098	
E	9.65	10.41	0.380	0.410
E1	6.22	8.50	0.245	0.335
e	2,54 BSC		0,100 BSC	
e1	4.28		0.169	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	1.02	1.68	0.040	0.066
W	typ. 0.02	0.040	typ. 0.0008	0.002

All dimensions conform with  
and/or within JEDEC standard.



## Thyristor

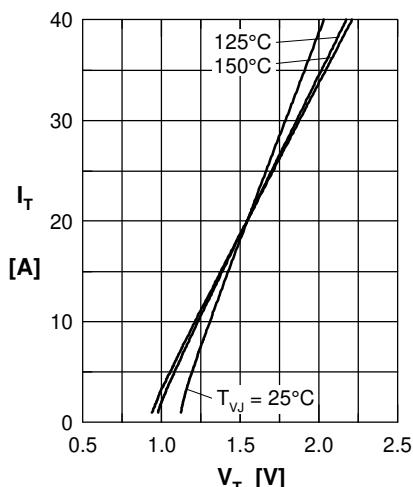


Fig. 1 Forward characteristics

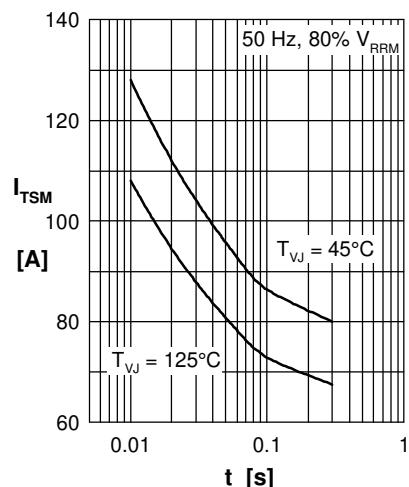


Fig. 2 Surge overload current

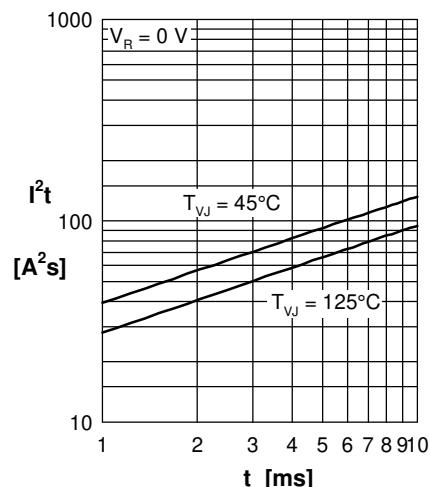


Fig. 3  $I^2t$  versus time (1-10 ms)

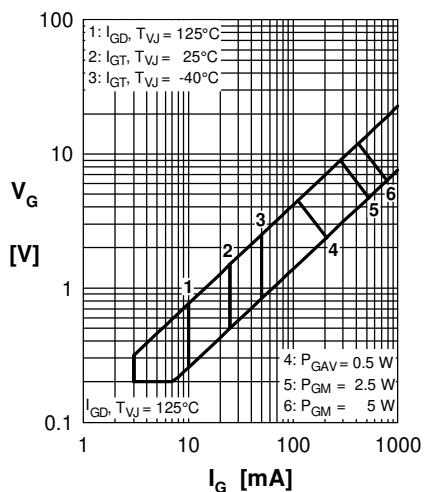


Fig. 4 Gate trigger characteristics

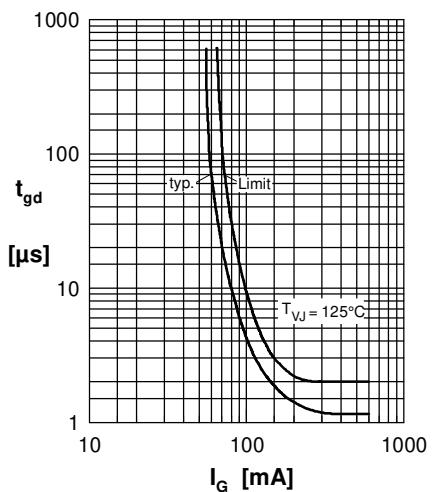


Fig. 5 Gate controlled delay time

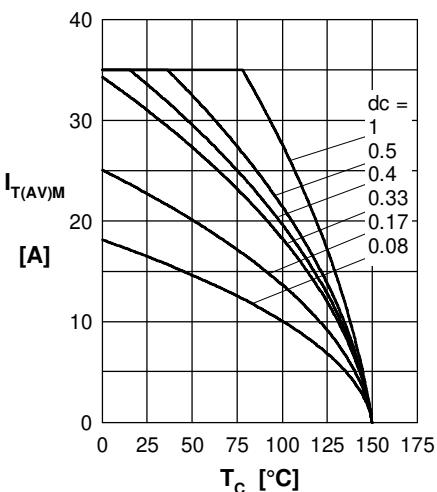


Fig. 6 Max. forward current at case temperature

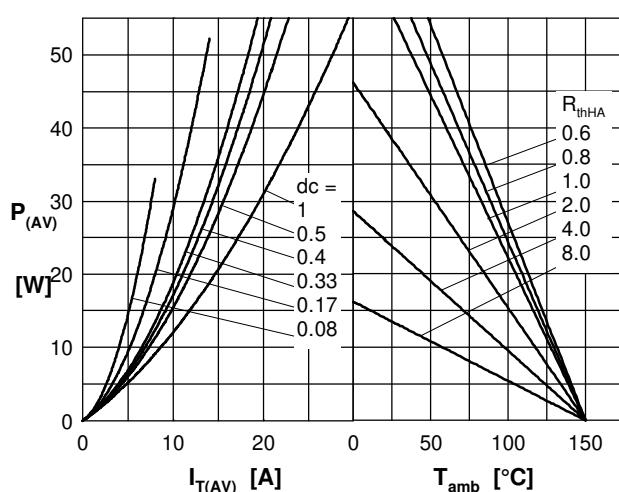


Fig. 7a Power dissipation versus direct output current  
Fig. 7b and ambient temperature

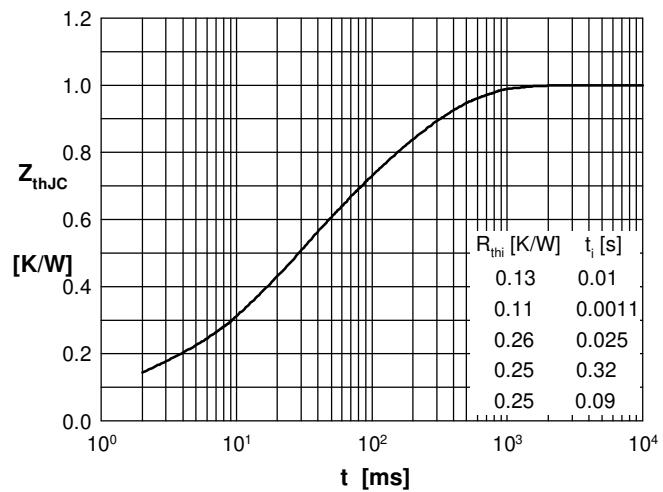


Fig. 8 Transient thermal impedance junction to case